

Declaration of Compliance

We declare that our green products for customer comply with all RoHS regulations. We are willing to provide all necessary documentation or information to prove our compliance with the RoHS regulations. It is our responsibility to proactively inform our customer if we identify that there is a potential risk of breaching the RoHS regulations in our product.

1. Product Information:

Model P/N:	Products P/N:
F0PEC4654T00Z	4610-54P-O-AC-F-TW v1
F0PEC4654701Z	4610-54P-O-AC-F-CN v1
F0PEC4654504Z	4610-54P-O-AC-F-JP v1
F0PEC4654406Z	4610-54P-O-AC-F-US v1
F0PEC4654303Z	4610-54P-O-AC-F-UK v1
F0PEC4654203Z	4610-54P-O-AC-F-EU v1
F0PEC4654014Z	4610-54P-O-AC-F v1
F0PEC4654013Z	4610-54P-OC-AC-F v1
F0PEC4654012Z	4610-54P-OI-AC-F v1

Product meets EU RoHS requirements by application of selected exemption(s):

Banned Substance	Threshold Limit	RoHS Exemption*
Lead (Pb)	1,000 ppm (0.1 weight %)	6(c); 7(a); 7(c)-I
Cadmium (Cd)	100 ppm (0.01 weight %)	
Mercury (Hg)	1,000 ppm (0.1 weight %)	
Hexavalent Chromium (Cr ⁶⁺)	1,000 ppm (0.1 weight %)	
Poly Brominated Biphenyls (PBB)	1,000 ppm (0.1 weight %)	
Poly Brominated Diphenyl Ethers (PBDE)	1,000 ppm (0.1 weight %)	
Bis(2-Ethylhexyl) phthalate (DEHP)	1,000 ppm (0.1 weight %)	
Benzyl butyl phthalate (BBP)	1,000 ppm (0.1 weight %)	
Dibutyl phthalate (DBP)	1,000 ppm (0.1 weight %)	
Diisobutyl phthalate (DIBP)	1,000 ppm (0.1 weight %)	

RoHS maximum limit (ppm) does not apply to applications for which exemptions have been granted by the RoHS Directive.

Applicable within the scope of categories and expiry dates as given in Annex III of Directive 2011/65/EU as listed below:

RoHS exemption	RoHS exemption description
6(c)	Copper alloy containing up to 4% lead by weight.
7(a)	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead).
7(c)-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.

This statement reflects Products listed below that are manufactured by Edgecore Technology Corporation are in compliance to Regulation (EC) No 1907/2006 of the European Parliament and of the Council of 18 December 2006 concerning the Registration, Evaluation, Authorization and Restriction of Chemicals (REACH). The Candidate List of SVHCs is continually updated at <https://echa.europa.eu/candidate-list-table>.

This product contains the following REACH Substances of Very High Concern above the limits (0.1% w/w) of component article within REACH:

CAS No.	SVHCs in a concentration above 0.1% weight by weight
1303-86-2	Diboron trioxide
1317-36-8	Lead monoxide (lead oxide)
25550-51-0	Hexahydromethylphthalic anhydride
7439-92-1	Lead
71868-10-5	2-methyl-1-(4-methylthiophenyl)-2-morpholinopropan-1-one

Table of toxic and hazardous substances/elements and their content:

(As required by China's management methods for controlling pollution by electronic information products)

产品内含有害物质揭露表 Products contain hazardous substances exposing table						
零部件名称 Component Name	有害物质项目 Hazardous Substances Project					
	铅 (Pb)	镉 (Cd)	汞 (Hg)	六价铬 (Cr6+)	多溴联苯 (PBB)	多溴二苯乙醚 (PBDE)
电源供应器 Power supply	X	○	○	○	○	○
风扇 FAN	X	○	○	○	○	○
电源线 Power Cord	X	○	○	○	○	○
间隔柱 SPACER	X	○	○	○	○	○
固态硬盘模块 eUSB MODULE	X	○	○	○	○	○
场效应晶体管 Mosfet	X	○	○	○	○	○
突波吸收器(静电保护) TVS Array	X	○	○	○	○	○
电压转换集成电路 Regulator	X	○	○	○	○	○
二极管 Diode	X	○	○	○	○	○
电阻 Resistor	X	○	○	○	○	○

本表格依据 SJ/T : 11364-2014 的规定编制。

○ : 表示此部件使用的所有同类材料中此种有毒或有害物质的含量均低于 GB/T 26572-2011 规定的限制要求。
 ○ : indicates the toxic or hazardous substance content of the part (at the homogenous material level) is lower than the threshold defined by Requirements for Concentration Limits for Toxic or hazardous Substances in Electronic Information Products (GB/T 26572-2011) issued by Chinese Ministry of Information Industry ("Not Contained" toxic or hazardous substances).

X: 表示此部件使用的至少一种同类材料中, 此种有毒或有害物质的含量高于 GB/T 26572-2011 规定的限制要求。
 X: indicates the toxic or hazardous substance content of the part (at the homogenous material level) is over the threshold defined by standard of GB/T 26572-2011 ("Contained" toxic or hazardous substances). Suppliers can explain the technical cause of "X" according to actual situation.

The declared Edgecore product(s) is (are) in compliance with the restriction identified in Article 11:

Banned Substance	Threshold Limit
Lead (Pb)	1,000 ppm (0.1 weight %)
Cadmium (Cd)	100 ppm (0.01 weight %)
Mercury (Hg)	1,000 ppm (0.1 weight %)
Hexavalent Chromium (Cr ⁶⁺)	1,000 ppm (0.1 weight %)
Poly Brominated Biphenyls (PBB)	1,000 ppm (0.1 weight %)
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The following tables are a declaration of the presence condition of restricted substances:

設備名稱：1G乙太網路交換機 Equipment name		型號（型式）：AS4610-54P Type designation (Type)				
單元 Unit	限用物質及其化學符號 Restricted substances and its chemical symbols					
	鉛 Lead (Pb)	汞 Mercury (Hg)	鎘 Cadmium (Cd)	六價鉻 Hexavalent chromium (Cr+6)	多溴聯苯 Polybrominated biphenyls (PBB)	多溴二苯醚 Polybrominated diphenyl ethers (PBDE)
電路板組件 PCBA	-	○	○	○	○	○
風扇 FAN	-	○	○	○	○	○
機殼 Chassis	-	○	○	○	○	○
線材 Cable Assy	○	○	○	○	○	○
電源線 Power Cord	-	○	○	○	○	○
電源供應器 Power Supply	-	○	○	○	○	○
<p>備考1. “超出0.1 wt %”及“超出0.01 wt %”係指限用物質之百分比含量超出百分比含量基準值。 Note 1: “Exceeding 0.1 wt %” and “exceeding 0.01 wt %” indicate that the percentage content of the restricted substance exceeds the reference percentage value of presence condition.</p> <p>備考2. “○”係指該項限用物質之百分比含量未超出百分比含量基準值。 Note 2: “○” indicates that the percentage content of the restricted substance does not exceed the percentage of reference value of presence.</p> <p>備考3. “-”係指該項限用物質為排除項目。 Note 3: The “-” indicates that the restricted substance corresponds to the exemption.</p>						

Name: 陳文輝 Wen Chen
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QA Representative

Signature :

Date : 2022-08-12

Wm. A. R.